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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Claim

A semiconductor device characterized by the fact that in a semiconductor device in which a second semiconductor chip smaller than a first semiconductor chip is connected on said first die-bonded semiconductor chip, a first bump is formed outside of the above-mentioned second semiconductor chip on the above-mentioned first semiconductor chip; that a second bump is formed on the above-mentioned second semiconductor chip; that a wiring pattern for connecting the above-mentioned first bump and the above-mentioned second bump is formed; that a transparent film for wiring is inserted between the above-mentioned first semiconductor chip and the above-mentioned second semiconductor chip; and that the above-mentioned first semiconductor chip and the above-mentioned second semiconductor chip are connected via the above-mentioned transparent film for wiring.

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